

	Type	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	2	"20040158409"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:36	
2	BRS	5	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3) with troubleshoot\$3 and micro-fabrication	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:58	
3	BRS	1324	700/117, 118, 183, 185.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 17:16	
4	BRS	1296	700/121.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:40	
5	BRS	440	714/46.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:41	
6	BRS	6	"6635872"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 14:47	

Type	Hits	Search Text	DBs	Time Stamp	Comments
IS&R	2	("5656811").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:43	
8	BRS 82	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3) with troubleshoot\$3 and (micro-fabrication or fabrication) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:58	
IS&R	2	("5938424").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 13:54	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	82	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with troubleshoot\$3 and (micro-fabrication or fabrication) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:53	
11	BRS	2	"20030120436"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 13:58	
12	BRS	8391	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:01	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
13	BRS	60	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and software	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:02	
14	BRS	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and software with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:03	

Type	Hits	Search Text	DBs	Time Stamp	Comments
15 BRS	7	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with beam\$1 and software with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:03	
16 BRS	21	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with beam\$1 and (program\$4 or software\$1) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:30	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
17	BRS	15	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (program\$4 or software\$1) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:04	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
18	BRS	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (program\$4 or software\$1 or cod\$3) with execut\$3 and user\$1 with interface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:47	

Type	Hits	Search Text	DBs	Time Stamp	Comments
19 BRS	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (tow or dual) with charg\$3 with beam\$1 and (program\$4 or software\$1) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:33	
20 BRS	3	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (tow or dual) with charg\$3 with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:33	



	Type	Hits	Search Text	DBs	Time Stamp	Comments
21	IS&R	2	("6635872").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/14 14:47	
22	BRS	0	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with troubleshoot\$3 and (micro-fabrication or fabrication) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and high with resolution with image\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:54	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
23	BRS	2	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with troubleshoot\$3 and (micro-fabrication or fabrication) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and high with resolution with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:56	
24	BRS	1173	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (micro-fabrication or fabrication) and high with resolution with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:56	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
25	BRS	184	(troubleshoot\$3 or inspect\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (micro-fabrication or fabrication) and high with resolution with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:57	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
26	BRS	70	(troubleshoot\$3 or inspect\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (micro-fabrication or fabrication) and high with resolution with imag\$3 and defect\$1 with (file\$1 dor database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:58	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
27	BRS	1	(troubleshoot\$3 or inspect\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (micro-fabrication or fabrication) and high with resolution with imag\$3 and initial\$2 with defect\$1 with (file\$1 dor database)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 14:58	
28	BRS	107	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical\$2 with analy\$4 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
29	BRS	4	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical\$2 with analy\$4 with exposed with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:34	
30	BRS	11	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical\$2 with analy\$4 with expos\$3 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:38	

Type	Hits	Search Text	DBs	Time Stamp	Comments
31 BRS	7	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and EDS with tool\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:41	
32 BRS	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and cross with section\$2 with three with dimension and EDS with tool\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:41	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and cross with section\$2 with dimension and EDS with tool\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:42	
34	BRS	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with section\$2)) with dimension and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:42	



	Type	Hits	Search Text	DBs	Time Stamp	Comments
35	BRS	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with section\$2)) with (3-d mor dimension\$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:43	
36	BRS	142	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with section\$2)) with (3-d mor dimension\$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:06	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
			(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with section\$2)) with (3-d mor dimension\$1) with EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:43	
37	BRS	1	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with section\$2)) with (3-d mor dimension\$1) with EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:43	
38	BRS	3	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (cross-section\$2 or (cross with section\$2)) with (3-d mor dimension\$1) same EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:45	

Type	Hits	Search Text	DBs	Time Stamp	Comments
39 BRS 3		(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and cut\$4 with (cross-section\$2 or (cross with section\$2)) with (3-d mor dimension\$1) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 15:53	
40 BRS 3		(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and cut\$4 with (cross-section\$2 or (cross with section\$2)) with (3-d or dimension\$1 or three-dimension\$2) and EDS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 16:21	

Type	Hits	Search Text	DBs	Time Stamp	Comments
41 BRS	307	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical\$2 with analy\$4 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:29	
42 BRS	46	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) with chemical\$2 with analy\$4 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:30	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
43	BRS	4	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) with chemical\$2 with analy\$4 with expos\$3 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:32	
44	BRS	4	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) with chemical\$2 adj analy\$4 with surface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
45	BRS	3	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and two with charg\$3 with particle\$1 with beam\$1 and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/14 17:49	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
46	BRS	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:18	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
47	BRS	2	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) same charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:22	



	Type	Hits	Search Text	DBs	Time Stamp	Comments
48	BRS	711	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 devices with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:04	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
49	BRS	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with device\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:27	

Type	Hits	Search Text	DBs	Time Stamp	Comments
50 BRS	2	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (dual or two) with charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:43	
51 BRS	2	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (dual or two) with charg\$3 with particle\$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:44	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
52	BRS	12	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (dual or two) with charg\$3 with particle\$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:45	
53	BRS	0	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and dual with charg\$3. with particle\$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:45	

Type	Hits	Search Text	DBs	Time Stamp	Comments
54 BRS	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and dual with charg\$3 with particle\$1 with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:46	
55 BRS	6	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and dual same charg\$3 with particle\$1 with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:50	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
56	BRS	2	jp-11213935-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/15 09:48	
57	BRS	45	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (two or dual) with charg\$3 with particle\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 09:56	

Type	Hits	Search Text	DBs	Time Stamp	Comments
58 BRS	12	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) same (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (two or dual) adj beams and charg\$3 with particle\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:00	
59 BRS	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:06	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
60	BRS	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams and (program\$4 or software\$1 or cod\$3) with execut\$3 and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:07	



	Type	Hits	Search Text	DBs	Time Stamp	Comments
61	BRS	5	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$ and (program\$4 or software\$1 or cod\$3) with execut\$3 and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:15	

Type	Hits	Search Text	DBs	Time Stamp	Comments
62 BRS	58	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:16	
63 BRS	16	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beams and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:17	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
64	BRS	18	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) with beam\$1 and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:20	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
65	BRS	16	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:25	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
66	BRS	0	(analy\$4 or diagnoss\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3) and computer with job\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
67	BRS	16	(analy\$4 or diagnos\$3). with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3) and computer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
68	BRS	16	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3) with computer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 16:12	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
69	BRS	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and (two or dual) adj beam\$1 and user\$1 with (interface or communicat\$3) with computer and receiv\$3 with request\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 10:34	



	Type	Hits	Search Text	DBs	Time Stamp	Comments
70	BRS	44	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 and ion with mill\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/15 16:45	
71	IS&R	2	("6539106").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/15 17:02	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
72	BRS	627	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with imag\$3 with value\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:07	
73	BRS	773	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with imag\$3 with value\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:07	

Type	Hits	Search Text	DBs	Time Stamp	Comments
74 BRS	53	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with. (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with imag\$3 with value\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:08	
75 BRS	1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with charged with particle with beam with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	

Type	Hits	Search Text	DBs	Time Stamp	Comments
76 BRS 1		analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with parameter\$1 same charged with particle with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	
77 BRS 17		analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with parameter\$1 and charged with particle with beam	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
78	BRS	17	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with parameter\$1 and charged with particle with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:09	
79	BRS	1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (calibrat\$3 or compensat\$3 or adjust\$3) with parameter\$1 and charged with particle with beam\$1 and relocat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:43	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
80	BRS	221	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:23	
81	BRS	11	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and SEM with chemical with analysis	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 10:44	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
82	BRS	2	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and user\$1 with (interface\$1 or communication\$1) with defin\$3 with (condition\$1 or state\$1 or status\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	
83	BRS	1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and pause same user\$1 with (interface\$1 or communication\$1) with defin\$3 with (condition\$1 or state\$1 or status\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:31	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
84	BRS	1	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and pause same user\$1 with (interface\$1 or communication\$1) with defin\$3 with (condition\$1 or state\$1 or status\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	
85	BRS	65	(defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and pause with user\$1 with (interface\$1 or communication\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	



	Type	Hits	Search Text	DBs	Time Stamp	Comments
86	BRS	1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and pause with user\$1 with (interface\$1 or communication\$1) and defin\$3 with (condition\$1 or state\$1 or status\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:32	
87	BRS	3	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and pause with user\$1 with (interface\$1 or communication\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 13:50	

	Type	Hits	Search Text	Dbs	Time Stamp	Comments
88	IS&R	2	("6539106").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 12:59	
89	BRS	320	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with electron with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 13:51	
90	BRS	401	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with electr\$4 with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 13:51	

Type	Hits	Search Text	DBs	Time Stamp	Comments
91 BRS	5	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with mill\$3 with object\$1 and electr\$4 with beam\$1 with imag\$3 with object\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:02	
92 BRS	1	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with mill\$3 and electr\$4 with beam\$1 with imag\$3 and computer with execut\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 14:04	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
93	BRS	5	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with mill\$3 and electr\$4 with beam\$1 with imag\$3 and computer and user\$1 with (interface\$1 or communicat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 14:06	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
94	BRS	3	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and ion with beam\$1 with mill\$3 and electr\$4 with beam\$1 with imag\$3 and computer and user\$1 with (interface\$1 or communicat\$3) and (delet\$3 or remov\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 14:06	

Type	Hits	Search Text	DBs	Time Stamp	Comments
95 BRS	39	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:03	
96 BRS	13	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:17	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
97	BRS	5	analys\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (Irelocat\$3 or locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:07	

Type	Hits	Search Text	DBs	Time Stamp	Comments
98	BRS 5	<p>analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1)</p>	<p>US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2005/07/18 15:08</p>	



Type	Hits	Search Text	DBs	Time Stamp	Comments
99 BRS 1	1	<p>analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with charged with beam\$1</p>	<p>US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2005/07/18 15:20</p>	

Type	Hits	Search Text	DBs	Time Stamp	Comments
100 BRS 11		analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with charged with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:09	
101 BRS 1		analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with charged with beam\$1 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:09	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
102	BRS	2	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3). with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (adjust\$3 or calibrat\$3 or compensat\$3) with charged with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:17	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
103	BRS	2	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomaly\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (adjust\$3 or calibrat\$3 or compensat\$3) with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:17	

Type	Hits	Search Text	DBs	Time Stamp	Comments
104 BRS	5	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:21	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
105	BRS 1		analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and align\$4 with beam\$1 with parameter\$1 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:22	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
			analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with previous\$2 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:23	

Type	Hits	Search Text	DBs	Time Stamp	Comments
107 BRS 5		<p>analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with (histor\$6 or previous\$2) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1)</p>	<p>US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB</p>	2005/07/18 15:24	



	Type	Hits	Search Text	DBs	Time Stamp	Comments
108	BRS	5	analy\$4 with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with (histor\$6 or previous\$2) with imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:24	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
109	BRS	6	<p>analy\$4 same (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with (histor\$6 or previous\$2) with imag\$3</p>	<p>US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB</p>	2005/07/18 15:26	

Type	Hits	Search Text	DBs	Time Stamp	Comments
110 BRS 1	1	<p>analy\$4 same (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and (adjust\$3 or calibrat\$3 or compensat\$3 or modify\$3 or chang\$3) with imag\$3 with magnif\$7 and (relocat\$3 or locat\$3 or re-locat\$3) with (histor\$6 or previous\$2) with imag\$3</p>	<p>US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB</p>	<p>2005/07/18 15:27</p>	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
111	BRS	6	analy\$4 same (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and control\$5 with stage\$1 with receiv\$3 with (position\$3 or locat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:48	
112	BRS	2	analy\$4 same (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charged with beam\$1 and control\$5 with stage\$1 with receiv\$3 with (position\$3 or locat\$4) with beam\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 15:48	

Type	Hits	Search Text	DBs	Time Stamp	Comments
113 BRS	17	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 with (two or dual)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 16:41	
114 BRS	1	(analy\$4 or diagnos\$3) with (defect\$1 or error\$1 or malfunction\$2 or problem\$1 or fault\$1 or fail\$3 or anomal\$3 or trouble\$1) with (semiconductor\$1 or wafer\$1 or IC\$1 or (integrated adj circuit\$1) or chip\$1 or die\$1) and charg\$3 with particle\$1 with beam\$1 with (two or dual) and path\$1 with travel\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/07/18 16:43	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
115	BRS	807	702/183.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 17:15	
116	BRS	2102	702/117, 118, 183, 185.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/07/18 17:16	